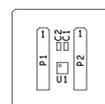| REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	19AUG21	P. DELCORRO

ASSEMBLY NOTES:

1. BOARD ACCEPTABILITY PER ANALOG DEVICES, INC. SPECIFICATION
    TST00119 (LATEST REVISION).

2. REPAIRS PER IPC-7711/21(LATEST REVISION) ARE ALLOWED.

3. REPAIRS ARE NOT ALLOWED IN SOLDERMASK FREE AREAS ON EITHER
    SIDE OF THE BOARD.

4. RoHS COMPLIANCE: ASSEMBLY VENDOR SHOULD ASSURE COMPLIANCE
    WITH LEAD-FREE AND RoHS PCB ASSEMBLY STANDARDS (EU RoHS
    DIRECTIVE 2002/95/EC).

5. SINGULATE BOARDS AFTER ASSEMBLY PROCESS.
    SMOOTHEN EDGES AND FREE FROM BURRS AFTER DEPANELIZATION PROCESS.

6. P1 & P2 CONNECTOR TO BE INSTALLED BY THE USER.

    ASSEMBLY HOUSE TO SHIP THE PART FOR P1 & P2 TOGETHER WITH ASSEMBLED BOARDS.

PRIMARY SIDE

EVAL-ADXL367Z

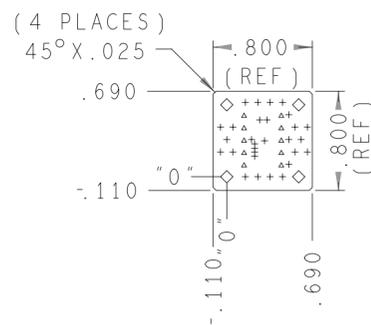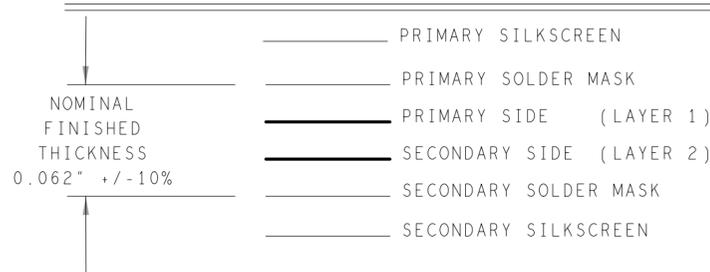| UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES	APPROVAL	DATE			
	TEMPLATE ENGINEER			WWM DIVISION	
TOLERANCES	HARDWARE SERVICES M. VALE	19AUG21	ANALOG DEVICES	804 WOBURN STREET WILMINGTON, MA 01887	
DECIMALS FRACTIONS ANGLES .XX +-.010 +-1/32 +- 2 .XXX +-.005 .XXXX +-.0050	HARDWARE SYSTEMS				
	TEST ENGINEER		TITLE		
MATERIAL	COMPONENT ENGINEER M. YAN	19AUG21	ASSEMBLY EVAL-ADXL367Z CUSTOMER EVALUATION Z		
	TEST PROCESS				
	HARDWARE RELEASE K. JABATAN	19AUG21			
FINISH	DESIGNER K. MOYO	19AUG21	SIZE	FSCM NO	DRAWING NUMBER	REV
	PTD ENGINEER P. DELCORRO	19AUG21	C	24355	01-069054	A
	CHECKER				
DO NOT SCALE DWG			SCALE 1/1		SHEET 1 OF 1

SPECIFICATIONS:

ROHS COMPLIANCE NOTE: HOMOGENOUS MATERIALS IN THIS BOARD SHALL BE COMPLIANT
THE EU RoHS DIRECTIVE 2002/95/EC

MATERIALS;   ALL LAMINATES AND BONDING MATERIALS SHOULD BE SELECTED FROM
IPC-4101 OR IPC-4103, MINIMUM Tg>170degC, Td>300degC,
U.L. RATING OF 94 V-0

MATERIAL FAMILY; ISOLA 370HR OR EQUIVALENT

CLADDING;   EXTERNAL LAYERS .5 OZ. COPPER, OVERPLATE TO 1.5 OZ.
~~INTERNAL SIGNAL LAYERS .5 OZ. COPPER.~~
~~INTERNAL PLANE LAYERS 1 OZ. COPPER.~~

NOTE: IF THE LAYER STACKUP CONFLICTS WITH THE ABOVE
CLADDING SPECIFICATIONS THEN THE LAYER STACKUP SHALL
TAKE PRECEDENCE.

SOLDER MASK;   SHALL BE LIQUID PHOTOIMAGEABLE (LPI) APPLIED ON BOTH SIDES
OVER BARE COPPER OR GOLD AND SHALL MEET IPC-SM-840
(LATEST REV.) CLASS 3. COLOR GREEN.

SILK SCREEN;   SHALL BE PERMANENT NON-CONDUCTIVE EPOXY INK, COLOR: WHITE
SYNTHETIC INKJET PRINTING ALLOWED FOR DENSE BOARDS,
COLOR: WHITE

SURFACE FINISH;   ENIG (ELECTROLESS NICKEL/IMMERSION GOLD)
PER IPC-4552 LATEST REVISION

INTENTIONAL SHORTS; IF SUPPLIED DATA INCLUDES A FILE "READ_ME.2", THEN
INTENTIONAL NET SHORTS EXIST. CUSTOMER REVIEW AND APPROVAL
IS REQUIRED IF SUPPLIED DATA REPORTS ANY CONDITION THAT
DOES NOT MATCH "READ_ME.2" FILE PROVIDED.

TEST REQUIREMENTS; 100% NETLIST ELECTRICAL VERIFICATION USING CUSTOMER
SUPPLIED IPC-D-356 NETLIST FOR OPENS AND SHORTS WHEN
"GERBER DATA" IS PROVIDED. THIS VERIFICATION ALSO
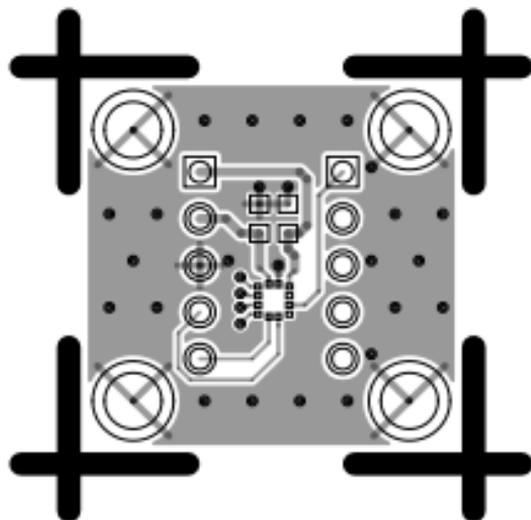REQUIRED FOR "ODB++" DATA PER EMBEDDED NETLIST.

REQUIREMENTS:

1.   REFER TO IPC-6010 SERIES (LATEST REV.), CLASS 2 FOR
FABRICATION UNLESS OTHERWISE SPECIFIED.

2.   ACCEPTABILITY PER ANALOG DEVICES, INC. SPECIFICATION TST00115,
(LATEST REVISION.)

3.   MODIFICATIONS TO THE ARTWORK ARE NOT ALLOWED WITHOUT
WRITTEN AUTHORIZATION.

4.   HOLE PATTERN TOLERANCES FOR UNDIMENSIONED HOLES SHALL BE
A DIAMETER OF 0.005 INCHES FROM THEIR TRUE POSITION.

5.   PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN 0.001 INCH
MINIMUM AVERAGE, WITH NO READING LESS THAN .0008 BY
CROSS SECTION.

6.   HOLE DIAMETERS APPLY AFTER PLATING.

7.   FINISHED CONDUCTOR WIDTHS SHALL NOT BE REDUCED FROM THE
NOMINAL INDICATED ON THE MASTER PATTERN, BY MORE THAN THE
CONDUCTOR THICKNESS.

8.   MINIMUM DESIGN LINE WIDTH IS .008 INCH.

9.   MINIMUM DESIGN SPACING IS .008 INCH.

~~10. NON-FUNCTIONAL PAD REMOVAL FROM INNER SIGNAL LAYERS MAY BE~~
~~PERFORMED AFTER CUSTOMER APPROVAL.~~

11. IF PAD SIZES PROVIDED ARE NOT LARGE ENOUGH TO MAINTAIN
ANNULAR RING REQUIREMENT, MFGR. MAY REQUEST APPROVAL TO
TEAR DROP PADS TO MAINTAIN ANNULAR RING. (AT PAD TO TRACE
INTERSECTION ONLY AND ELECTRICAL INTEGRITY MUST BE MAINTAINED.)

12. THIEVING MAY BE ADDED TO COMPENSATE FOR LOW COPPER DENSITY
AREAS ON THIS DESIGN ONLY AFTER REVIEW AND APPROVAL FROM
THE CUSTOMER:

A. THIEVING TO CARD EDGE, FIDUCIALS, NON-PLATED THROUGH HOLES,
ALL OTHER FEATURES TO BE 0.200 INCH MINIMUM.
B. THERE SHALL BE NO THIEVING IN ANY AREAS FREE OF SOLDER
MASK OR INTERNAL COPPER PLANES.

13. MFGR. TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT
NON-CONDUCTIVE INK ON SECONDARY SIDE IN A CLEAR AREA
UNLESS OTHERWISE INDICATED;

A. U.L. CODE-FLAMMABILITY RATING   D. MFGR LOGO
B. DATE CODE (STAMP).   E. SUCCESSFUL ELECTRICAL TEST.
C. LOT NUMBER

14. REPAIRS PER IPC-7711/21 (LATEST REV.) ARE ALLOWED.

15. BOARDS TO BE SHIPPED IN ARRAY AND KEEP INTACT.
PANEL TO BE SUBJECTED TO CUSTOMER'S APPROVAL.
PANELED SOLDER PASTE STENCIL SHOULD BE SENT TO CUSTOMER.

(4 PLACES)
45°X.025
.800 (REF)
.690
.800 (REF)
-.110
"0"
-.110
.690

HOLE TOLERANCE

UNLESS SPECIFIED
PLATED: +/-3MILS
NON PLATED: +/-2MILS

DRILL CHART:TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	PLATED	QTY	TOLERANCE/NOTES
+	10.0	PLATED	29	DIA MAX
△	45.0	PLATED	10	
◇	120.0	PLATED	4	

2 LAYER STACKUP

PRIMARY SILKSCREEN
PRIMARY SOLDER MASK
PRIMARY SIDE   (LAYER 1)
SECONDARY SIDE   (LAYER 2)
SECONDARY SOLDER MASK
SECONDARY SILKSCREEN

NOMINAL
FINISHED
THICKNESS
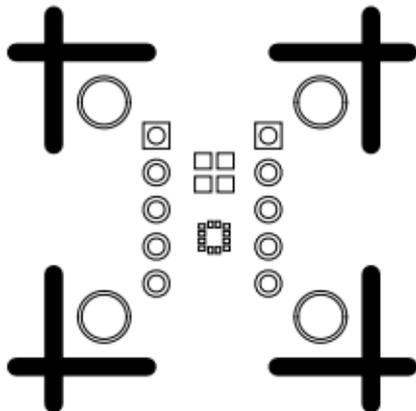0.062" +/-10%

PRIMARY SIDE
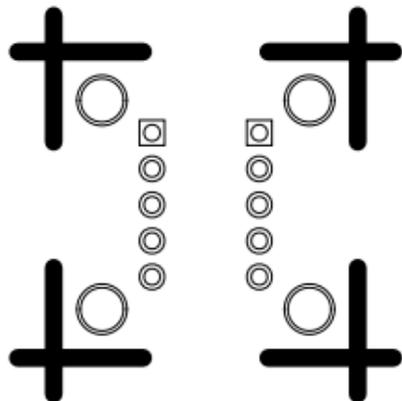
EVAL-ADXL367Z

L1 PRIMARY
08-069054-01
REV A

SOLDERMASK PRIMARY
08-069054-04
REV A

SOLDERMASK SECONDARY
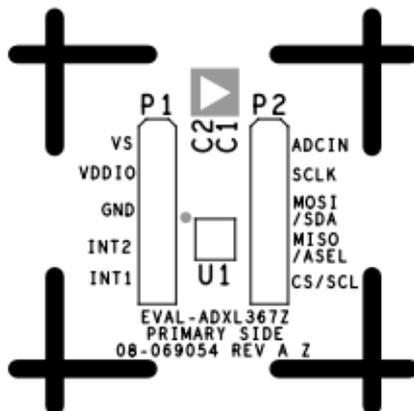08-069054-06
REV A

PASTEMASK PRIMARY
08-069054-07
REV A

SILKSCREEN PRIMARY
08-069054-03
REV A

P1 P2

VS   ADCIN
VDDIO   SCLK
GND   MOSI
            /SDA
INT2   MISO
            /ASEL
INT1   CS/SCL

U1

EVAL-ADXL367Z
PRIMARY SIDE
08-069054 REV A Z

SILKSCREEN SECONDARY
08-069054-05
REV A

SECONDARY SIDE
08-069054 REV A

L2 SECONDARY
08-069054-02
REV A